GOVERNMENT OF ANDHRA PRADESH
ABSTRACT

IT, E&C Dept - Promotions Wing – Approval to M/s. Hindalco Industries Limited for setting-up Integrated Aluminum Extrusion Facility in Kuppam, Chittoor District, Andhra Pradesh, and consideration of the project under the AP Electronics Component Manufacturing Policy (4.0) 2025-30 for extending incentives towards a proposed investment of INR 586 Crores with potential to create 613 jobs – Orders – Issued.

INFORMATION TECHNOLOGY, ELECTRONICS AND COMMUNICATION [IT,E&C] (PROMOTIONS) DEPARTMENT

G.O.MS.No. 37

Dated: 09-09-2025
Read the following

1. G.O.Ms.No.30, IT, E&C (Promotion Wing) Department, date: 01.08.2025.
2. Proposal of M/s. Hindalco Industries Limited
3. NF.No.APEDB-11/116/2025-INT PRM-APEDB, dated: 13.08.2025
4. Minutes of the 13th State Investment Promotion Committee Meeting held on 22.08.2025
5. Minutes of the 10th State Investment Promotion Board Meeting held on 28.08.2025
6. G.A. (CABINET) Department, U.O.No.396/2025, date: 04.09.2025

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ORDER:

1. The Government of Andhra Pradesh is actively pursuing strategic initiatives to position the state as a premier destination for investments in electronics components manufacturing. Recognizing that electronic components constitute a critical segment in the electronics value chain, the government is focused on fostering an ecosystem that supports innovation, scalability, and global competitiveness in this sector. By leveraging its strategic location, skilled workforce, and progressive governance, Andhra Pradesh aims to emerge as a hub for electronics components manufacturing, thereby playing a pivotal role in India's broader vision of becoming a global electronics manufacturing powerhouse.
2. In the reference 1, the Government of Andhra Pradesh issued the Electronics Component Manufacturing Policy (4.0) 2025-30 to capitalize on opportunities

(P.T.O)

in electronic component manufacturing. The policy focuses on establishing the state as a leader in electronics component manufacturing by fostering innovation, attracting investments, creating jobs, and building a robust manufacturing ecosystem.

3. In the reference 2, M/s Hindalco Industries Limited submitted a proposal to establish an Integrated Extrusion Facility in Kuppam, Andhra Pradesh, with a proposed investment of INR 586 Crores. The project has employment potential of 613 jobs. The company requested to sanction incentives under the Andhra Pradesh Electronics Component Manufacturing Policy (4.0), 2025–30.
4. In the reference 3, the Andhra Pradesh Economic Development Board (APEDB) confirmed that the proposed Integrated Aluminum Extrusion Facility (primary raw material for manufacturing mobile phone enclosures/chassis) falls under the Electronics Components Manufacturing Policy of the Government of Andhra Pradesh and is classified under Category D: “Supply Chain Ecosystem and Capital Equipment” of the Government of India ECMS Policy. The APEDB confirmed that this is among the first ten projects under the policy, making it eligible for applicable incentives. After evaluation, APEDB recommended the proposal to the Consultative Committee on Information Technology and Electronics Investments (CCITEI), which, in its meeting held on 14.08.2025, forwarded the proposal to the State Investment Promotion Committee (SIPC). The SIPC, in its meeting on 22.08.2025, approved the proposal and recommended to place before the State Investment Promotion Board (SIPB).
5. Accordingly, the proposal was placed before the SIPB in its meeting held on 28.08.2025. The SIPB, based on the recommendations from SIPC, decided as follows:

   "Project approval accorded for M/s Hindalco Industries Ltd to set up a manufacturing plant for Integrated Aluminum Extorsion Facility (primary raw material for manufacturing mobile phone enclosers/ chassis) with a proposed investment of INR 586 Cr. and employment of 613, offering early bird incentives under AP Electronics Component Manufacturing (AP ECMS) policy (4.0) 2025-30, subject to condition that the company should obtain approval from MeitY, GoI".

6. The Government, after careful examination of the proposal and considering the recommendations of the SIPB and the Honorable Council of Ministers, hereby accords approval to M/s Hindalco Industries Ltd for setting up a manufacturing plant for an Integrated Aluminum Extrusion Facility (primary raw material for manufacturing mobile phone enclosures/chassis) with a proposed investment of INR 586 Crore and an employment potential of 613.

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The project shall be extended early bird incentives under the AP Electronics Component Manufacturing (AP ECMS) Policy (4.0) 2025–30, subject to the condition that the company shall obtain necessary approval from MeitY, Government of India.

7. The MD, APTS and VC& MD, APIIC, Mangalagiri, shall take necessary action.

(BY ORDER AND IN THE NAME OF THE GOVERNOR OF ANDHRA PRADESH)

BHASKAR KATAMNENI
SECRETARY TO GOVERNMENT

To
M/s. Hindalco Industries Limited
The Secretary, Ministry of Electronics & Information Technology (MeitY), GoI.
The Spl. Chief Secretary to Government, Revenue (CT) Department
The Secretary to Govt., Industries and Commerce Dept.
The VC&MD, APIIC Ltd, Vijayawada.
The Principal Secretary to Government, Finance Department
The Principal Secretary to Government, Energy, I&I Department
The Principal Secretary to Government, MA&UD Dept.
The Director, Industries, Andhra Pradesh
The CEO, Andhra Pradesh Economic Development Board
The District Collector and Magistrate, Chittoor District.
The CMD, APSPDCL, Tirupati.
The MD, APTS, Vijayawada

Copy to:
The OSD to Hon'ble Minister for Information Technology, Andhra Pradesh
The PS to Principal Secretary to Hon'ble Chief Minister
The LET & F (Employment) Department.
The Law (B) Department
The GM, DIC, Chittoor
The ZM, APIIC, Chittoor
The P.S. to Secretary to Government & CIP
The P.S. to Secretary/Special Secretary to Government, IT, E&C Department
SC/SF